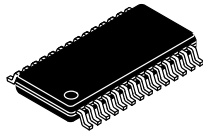


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

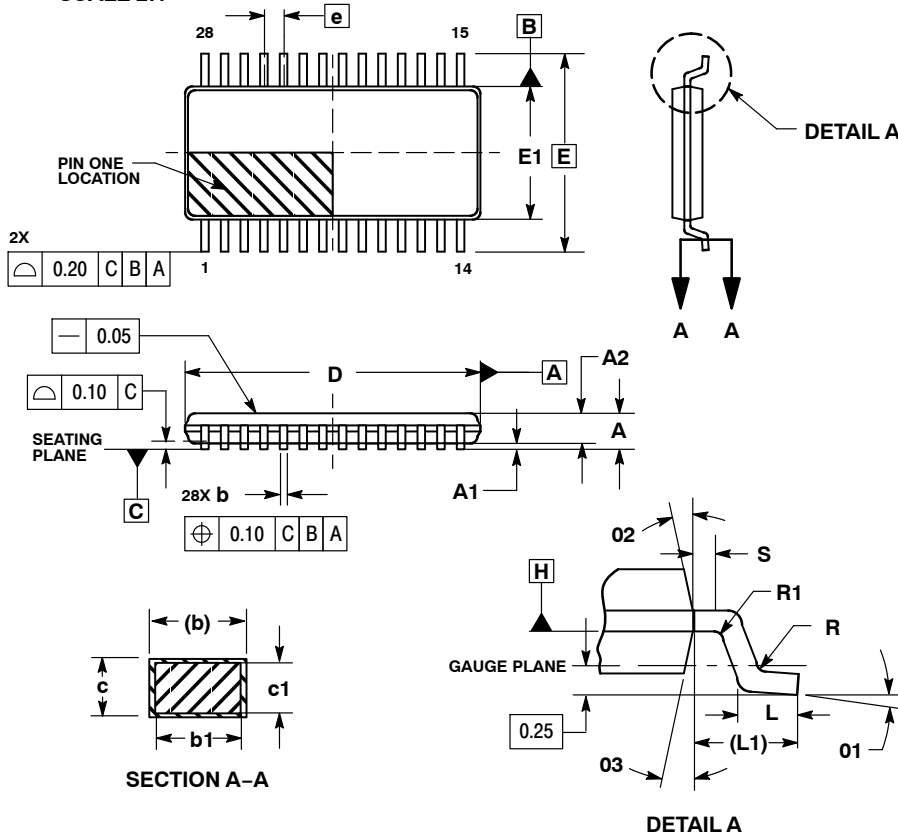
ON Semiconductor®



**TSSOP-28**  
CASE 948AC-01  
ISSUE O

DATE 24 JUN 2008

SCALE 2:1

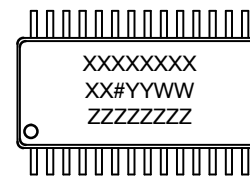


**NOTES:**

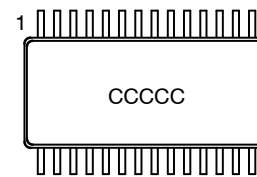
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION  $b$  DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

MILLIMETERS		
DIM	MIN	MAX
A	---	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
b1	0.19	0.25
c	0.09	0.20
c1	0.09	0.16
D	9.60	9.80
E	6.40 BSC	
E1	4.30	4.50
e	0.65 BSC	
L	0.45	0.75
L1	1.00 REF	
R	0.09	---
R1	0.09	---
S	0.20	---
01	0°	8°
02	12° REF	
03	12° REF	

**GENERIC MARKING DIAGRAM\***



TOP MARKING



BOTTOM MARKING

<b>DOCUMENT NUMBER:</b>	98AON30972E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	28 LEAD TSSOP, 9.7X4.4 MM, 0.65 PITCH	<b>PAGE 1 OF 2</b>

